12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240613007.1
Qualification of CDAT as an additional Assembly site for select devices
Change Notification / Sample Request

Date: June 13, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240613007.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM25180NGUR	NULL
LM25183NGUR	NULL
LM25184NGUR	NULL
LM5180NGUR	NULL
LM5181NGUR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240613007.1	PCN Date:	June 13, 2024
Title:	Qualification of CDAT as an alternate Assembly site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	September 11, 2024	Sample Requests accepted until:	July 13, 2024

***Sample requests received after** July 13, 2024 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for set of devices listed below. Material differences between sites as follows:

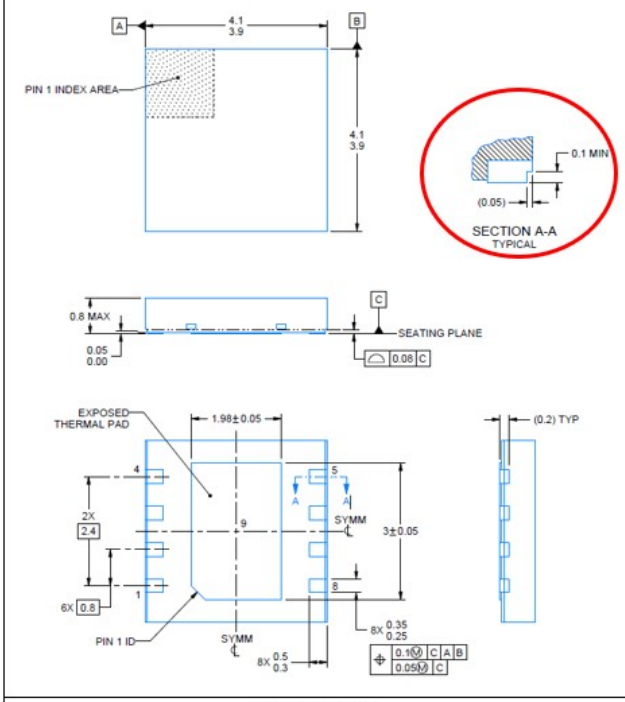
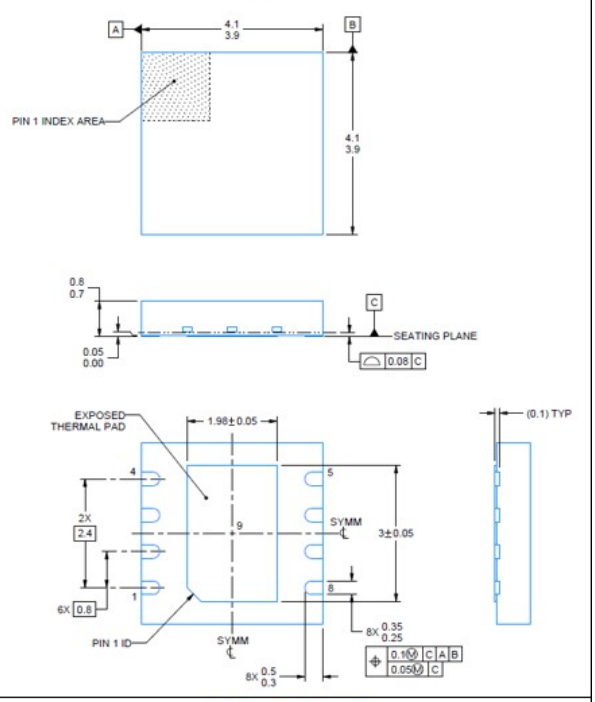
Group 1 Device

	UTL1	CDAT
Wire diam/type	1.3mil Cu	1.0mil Cu
Mount Compound	PZ0035	4207123
Lead finish	Matte Sn	NiPdAu

Group 2 Device

	UTL1	CDAT
Mount Compound	PZ0035	4207123
Lead finish	Matte Sn	NiPdAu

Package Outline Differences:

UTAC	TI CDAT
	
Wettable Flank	Non-Wettable Flank

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL1	NSE	THA	Bangkok
CDAT	**CDA**	**CHN**	**Chengdu**

G3 = Matte Sn
G4 = NiPdAu

Sample product shipping label (not actual product label)

Group 1 Product Affected:

LM25180NGUR	LM5181NGUR
LM5180NGUR	

Group 2 Product Affected:

LM25183NGUR	LM25184NGUR

Group 1 Qualification Results

Approve Date 25-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM25184QNGURQ1	QBS Reference: UCC27282QDRCRQ1	QBS Reference: PDRV8889QWRGERQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	3/135/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0	3/90/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	3/90/0

QBS: Qual By Similarity
Qual Device LM5180NGUR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Group 2 Qualification Results

Approve Date 25-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM25184QNGURQ1	QBS Reference: UCC27282QDRCRQ1	QBS Reference: PDRV8889QWRGERQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	3/135/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	1/15/0	3/90/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	3/30/0	3/30/0

QBS: Qual By Similarity
Qual Device LM25184NGUR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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